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| <b>INFORMATION DISCLOSURE<br/>STATEMENT BY APPLICANT</b><br><br><i>(Use as many sheets as necessary)</i> |   |    |   | Application Number: 10/055,560<br>Filing Date: January 22, 2002<br>First Named Inventor: Mou-Shiung Lin<br>Art Unit: 2813<br>Examiner Name: James M. Mitchell |  |
| Sheet  | 1 | of | 1 | Attorney Docket No: 085027-0058   |  |

**US PATENT DOCUMENTS**

| Examiner Initials* | Cite No | Document Number | Publication Date | Name of Patentee or Applicant of Cited Document | Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear |
|--------------------|---------|-----------------|------------------|---|---|
| 1                  | 5073814 | 12/17/1991      | Cole             |   |   |
| 2                  | 6492723 | 12/3/2002       | Suyama           |   |   |

**FOREIGN PATENT DOCUMENTS**

| Examiner Initials* | Cite No  | Foreign Patent Document | Publication Date | Name of Patentee or Applicant of cited Document | Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear | T* |
|--------------------|----------|-------------------------|------------------|---|---|----|
| 3                  | TW241438 | 2/21/1995               | Fuji Denki KKJP  |   |   | X  |

**OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS**

| Examiner Initials* | Cite No | Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published. | T* |
|--------------------|---------|---|----|
| 4                  |         | "Electronic Materials Handbook, Volume 1 – Packaging: Other Design Considerations; Materials and Electronic Phenomena; Physical Characteristics of Microelectronic Materials" ASM International Handbook Committee, pgs. 104-111, ASM International (1989)      |    |
| 5                  |         | KUO, "Semiconductor Packaging Engineering", Zhan Yi-Zheng Publisher, Registration Taipei, April 2000, Table 9.1   | X  |

**EXAMINER****DATE CONSIDERED**